

FDC6318P

Dual P-Channel 1.8V PowerTrench® Specified MOSFET

General Description

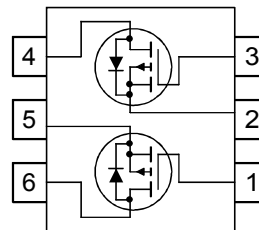
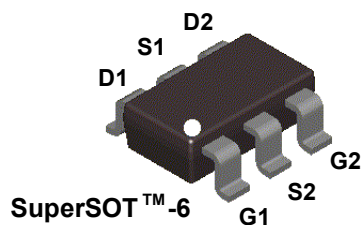
These P-Channel 1.8V specified MOSFETs are produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize on-state resistance and yet maintain low gate charge for superior switching performance.

Applications

- Power management
- Load switch

Features

- -2.5 A, -12 V. $R_{DS(ON)} = 90\text{ m}\Omega$ @ $V_{GS} = -4.5\text{ V}$
 $R_{DS(ON)} = 125\text{ m}\Omega$ @ $V_{GS} = -2.5\text{ V}$
 $R_{DS(ON)} = 200\text{ m}\Omega$ @ $V_{GS} = -1.8\text{ V}$
- High performance trench technology for extremely low $R_{DS(ON)}$
- SuperSOT™-6 package: small footprint (72% smaller than standard SO-8); low profile (1mm thick)



Absolute Maximum Ratings

$T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain-Source Voltage	-12	V
V_{GSS}	Gate-Source Voltage	± 8	V
I_D	Drain Current – Continuous (Note 1a)	-2.5	A
	– Pulsed	-7	
P_D	Power Dissipation for Single Operation (Note 1a)	0.96	W
	(Note 1b)	0.9	
	(Note 1c)	0.7	
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	130	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	60	$^\circ\text{C/W}$

Package Marking and Ordering Information

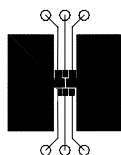
Device Marking	Device	Reel Size	Tape width	Quantity
.318	FDC6318P	13"	12mm	3000 units

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

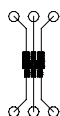
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV _{DSS}	Drain–Source Breakdown Voltage	V _{GS} = 0 V, I _D = –250 μA	–12			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I _D = –250 μA, Referenced to 25°C		–2.9		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = –10 V, V _{GS} = 0 V			–1	μA
I _{GSSF}	Gate–Body Leakage, Forward	V _{GS} = 8 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate–Body Leakage, Reverse	V _{GS} = –8 V, V _{DS} = 0 V			–100	nA
On Characteristics (Note 2)						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = –250 μA	–0.4	–0.7	–1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I _D = –250 μA, Referenced to 25°C		2.3		mV/°C
R _{DS(on)}	Static Drain–Source On–Resistance	V _{GS} = –4.5 V, I _D = –2.5 A V _{GS} = –2.5 V, I _D = –2 A V _{GS} = –1.8 V, I _D = –1.6 A V _{GS} = –4.5 V, I _D = –2.5A, T _J = 125°C		69 93 135 85	90 125 200 120	mΩ
I _{D(on)}	On–State Drain Current	V _{GS} = –4.5 V, V _{DS} = –5 V	–6			A
g _{FS}	Forward Transconductance	V _{DS} = –5 V, I _D = –2.5 A		8		S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = –6 V, V _{GS} = 0 V, f = 1.0 MHz		455		pF
C _{oss}	Output Capacitance			194		pF
C _{rss}	Reverse Transfer Capacitance			134		pF
Switching Characteristics (Note 2)						
t _{d(on)}	Turn–On Delay Time	V _{DD} = –6 V, I _D = –1 A, V _{GS} = –4.5 V, R _{GEN} = 6 Ω		9	18	ns
t _r	Turn–On Rise Time			14	25	ns
t _{d(off)}	Turn–Off Delay Time			21	34	ns
t _f	Turn–Off Fall Time			17	31	ns
Q _g	Total Gate Charge	V _{DS} = –6 V, I _D = –2.5 A, V _{GS} = –4.5 V		5.4	8	nC
Q _{gs}	Gate–Source Charge			1.1		nC
Q _{gd}	Gate–Drain Charge			1.3		nC
Drain–Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain–Source Diode Forward Current				–0.8	A
V _{SD}	Drain–Source Diode Forward Voltage	V _{GS} = 0 V, I _S = –0.8 A (Note 2)		–0.7	–1.2	V

Notes:

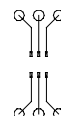
1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 130°C/W when mounted on a 0.125 in^2 pad of 2 oz. copper.



b) 140°C/W when mounted on a $.004\text{ in}^2$ pad of 2 oz copper



c) 180°C/W when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width $< 300\mu\text{s}$, Duty Cycle $< 2.0\%$

Typical Characteristics

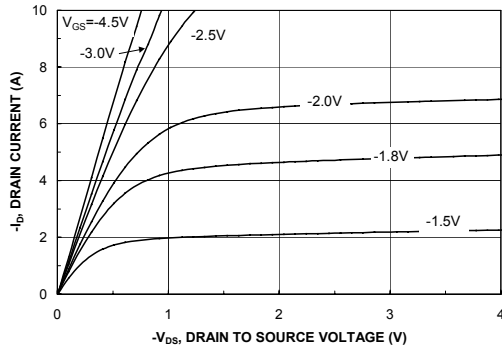


Figure 1. On-Region Characteristics.

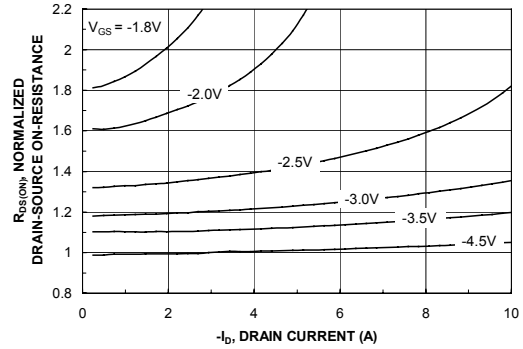


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

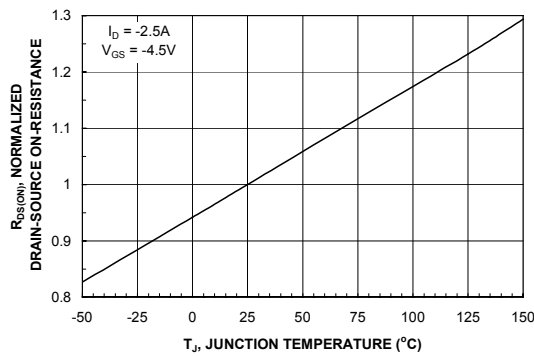


Figure 3. On-Resistance Variation with Temperature.

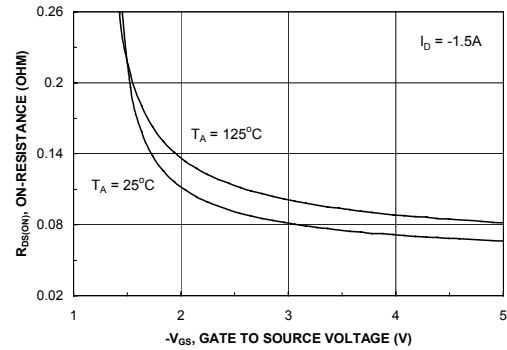


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

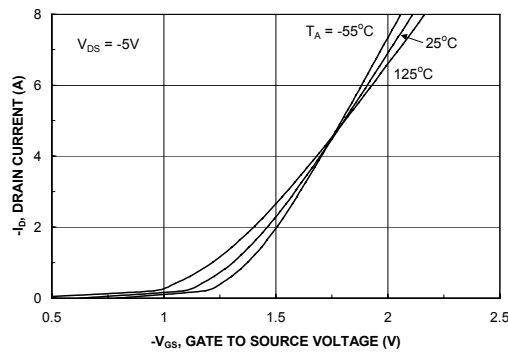


Figure 5. Transfer Characteristics.

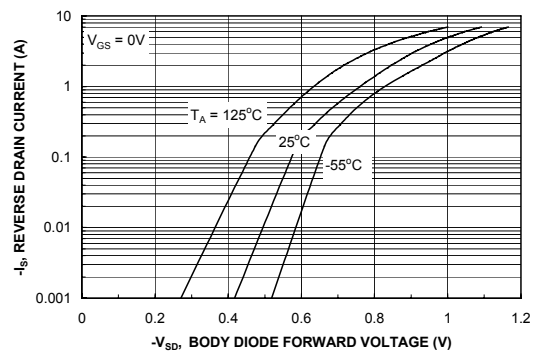


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics

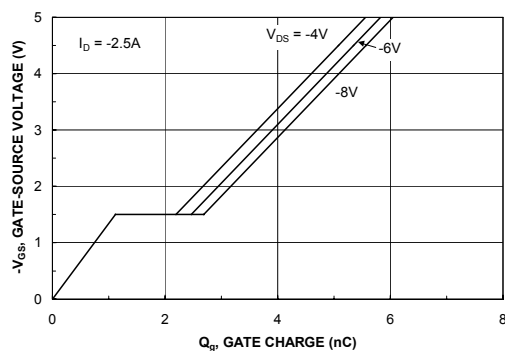


Figure 7. Gate Charge Characteristics.

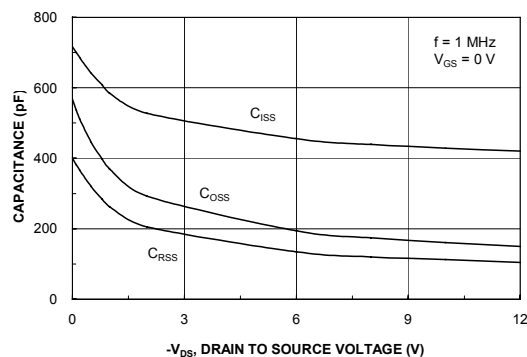


Figure 8. Capacitance Characteristics.

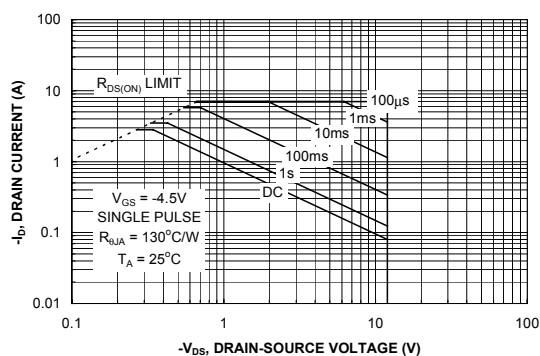


Figure 9. Maximum Safe Operating Area.

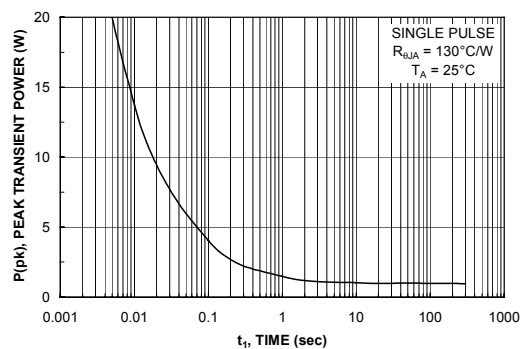


Figure 10. Single Pulse Maximum Power Dissipation.

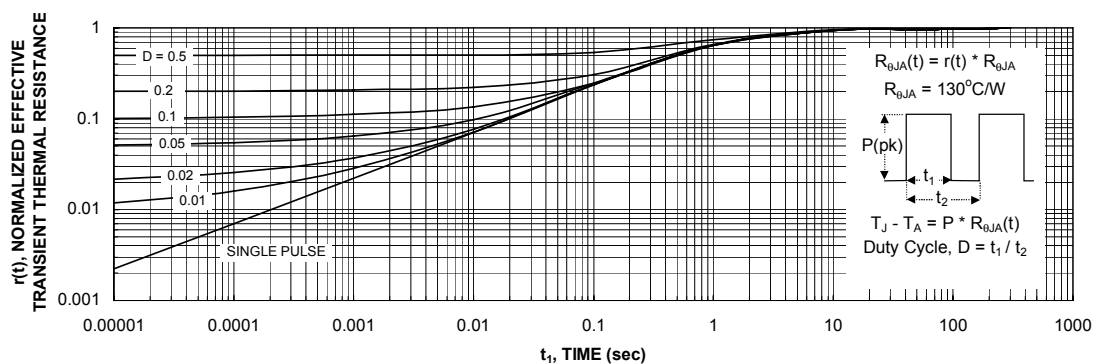


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b.
Transient thermal response will change depending on the circuit board design.

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